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Takahashi

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(54) **INK JET RECORDING HEAD AND METHOD OF MANUFACTURING THE SAME, AND INK JET RECORDING APPARATUS**

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(30) **Foreign Application Priority Data**

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(51) **Int. Cl.**[7] **B41J 2/045**
(52) **U.S. Cl.** **347/70**
(58) **Field of Search** 347/68–72; 29/890.1, 29/25.35

(56) **References Cited**

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(57) **ABSTRACT**

An ink jet recording head having a passage forming substrate made of a silicon monocrystalline substrate having pressure generating chambers communicating with nozzle orifices, and piezoelectric elements being formed on one of surfaces of the passage forming substrate with vibration plates interposed therebetween, each piezoelectric element including a lower electrode film, a piezoelectric layer and an upper electrode, wherein, wide portions, longitudinally extending, are provided on the vibration plate side of the pressure generating chambers, grooves, while extending in the longitudinal direction of the wide portion, are formed on both sides of each wide portion of the passage forming substrate, and the etching stop layers which define the side walls of each wide portion as viewed in the width direction to restrict the spread of the etching in the width direction of the pressure generating chamber, are put in the grooves.

7 Claims, 6 Drawing Sheets

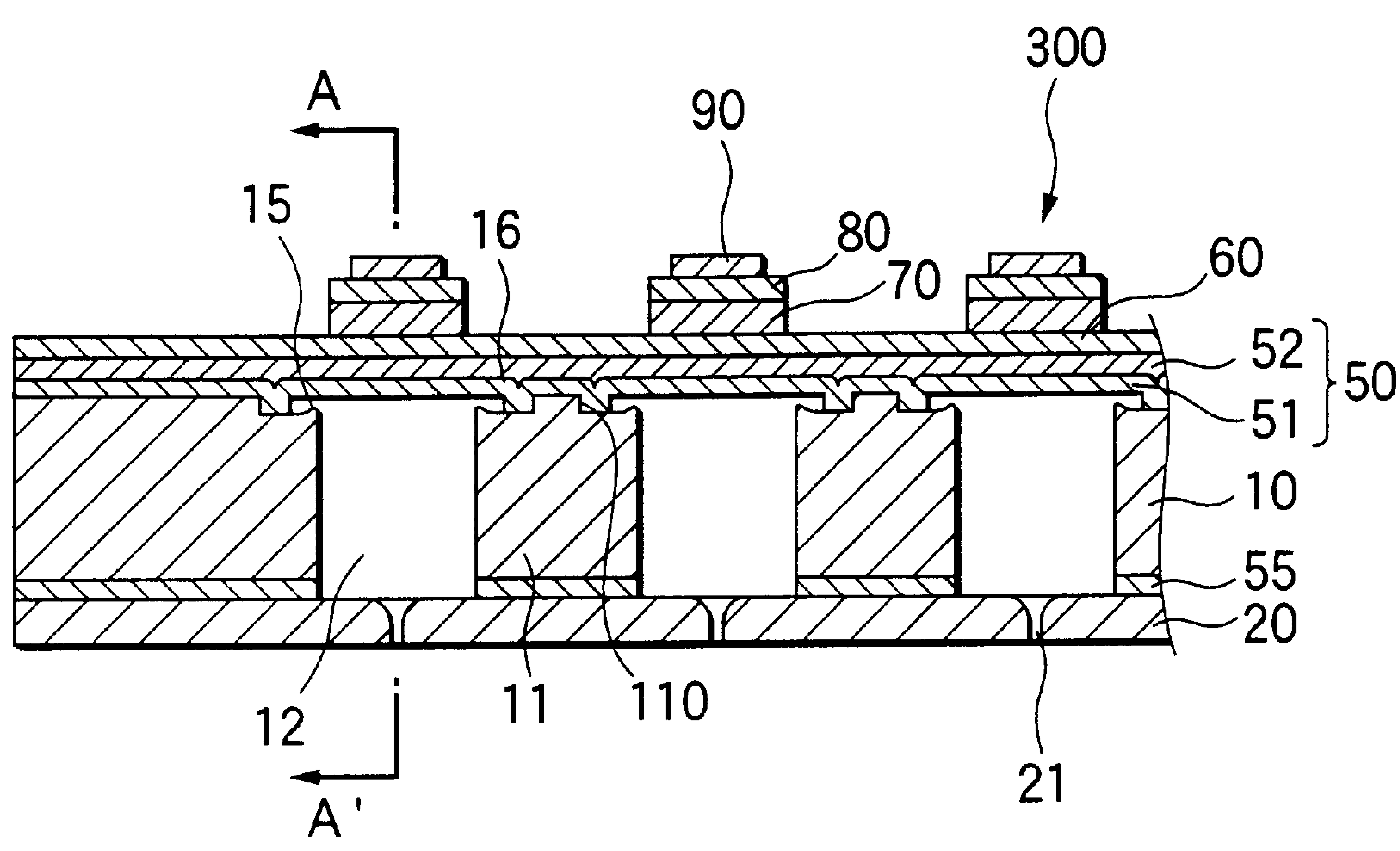


FIG.1

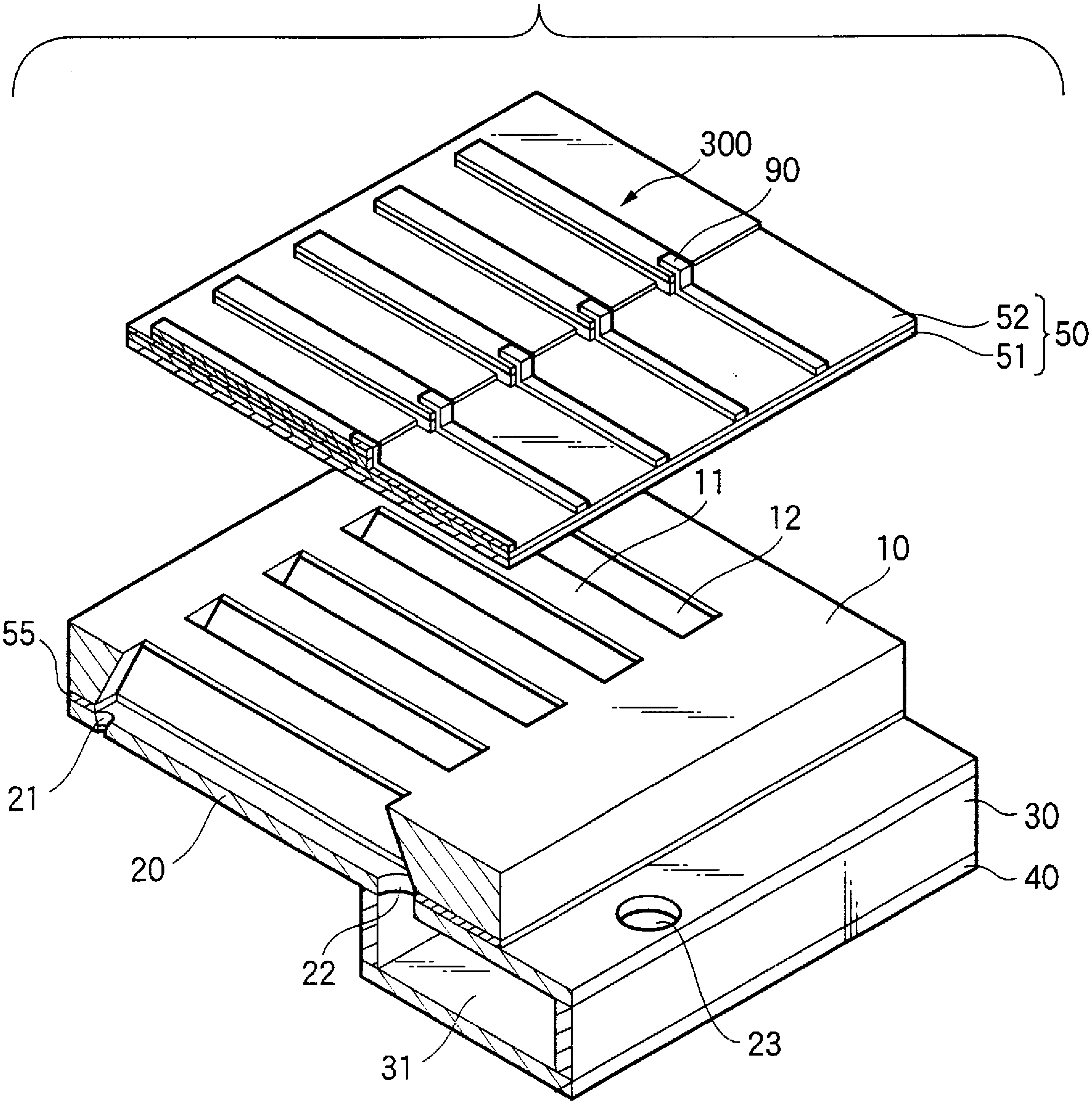


FIG.2A

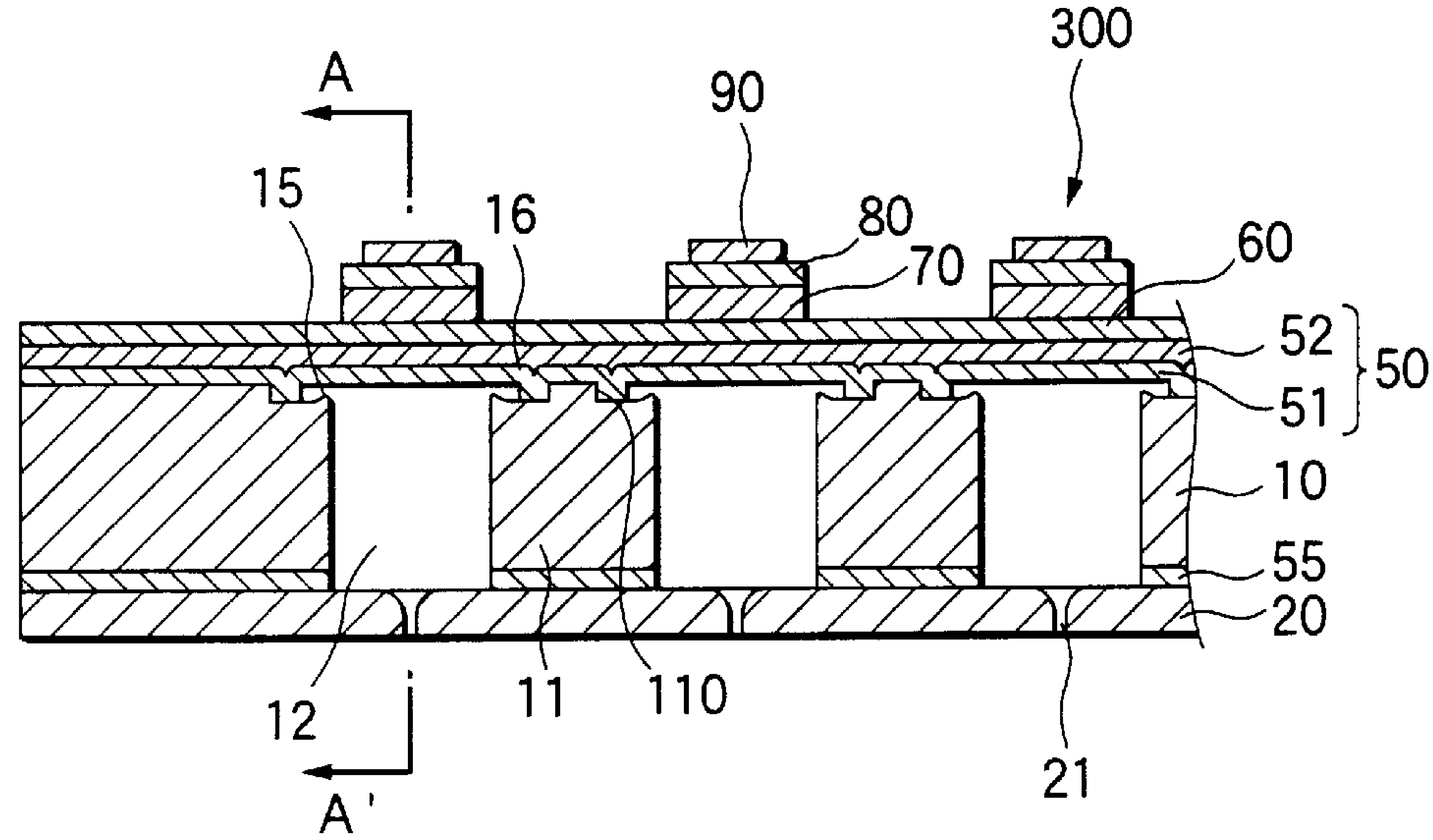

A
300
90
15
16
80
70
60
52
50
51
10
55
20
12
11
110
21
A'

FIG.2B

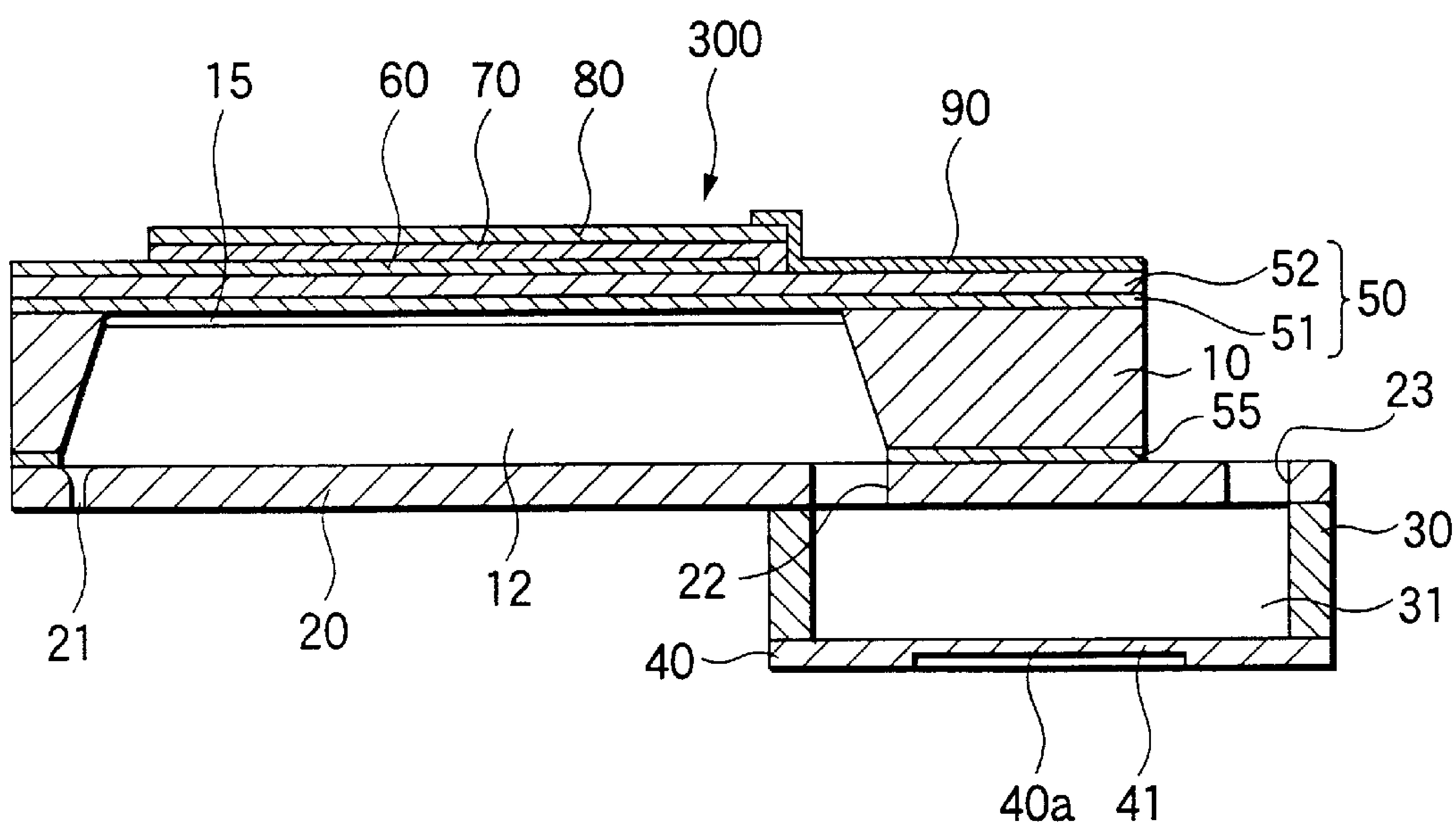

300
15
60
70
80
90
52
50
51
10
23
55
30
31
22
21
20
12
40
40a
41

FIG.3A

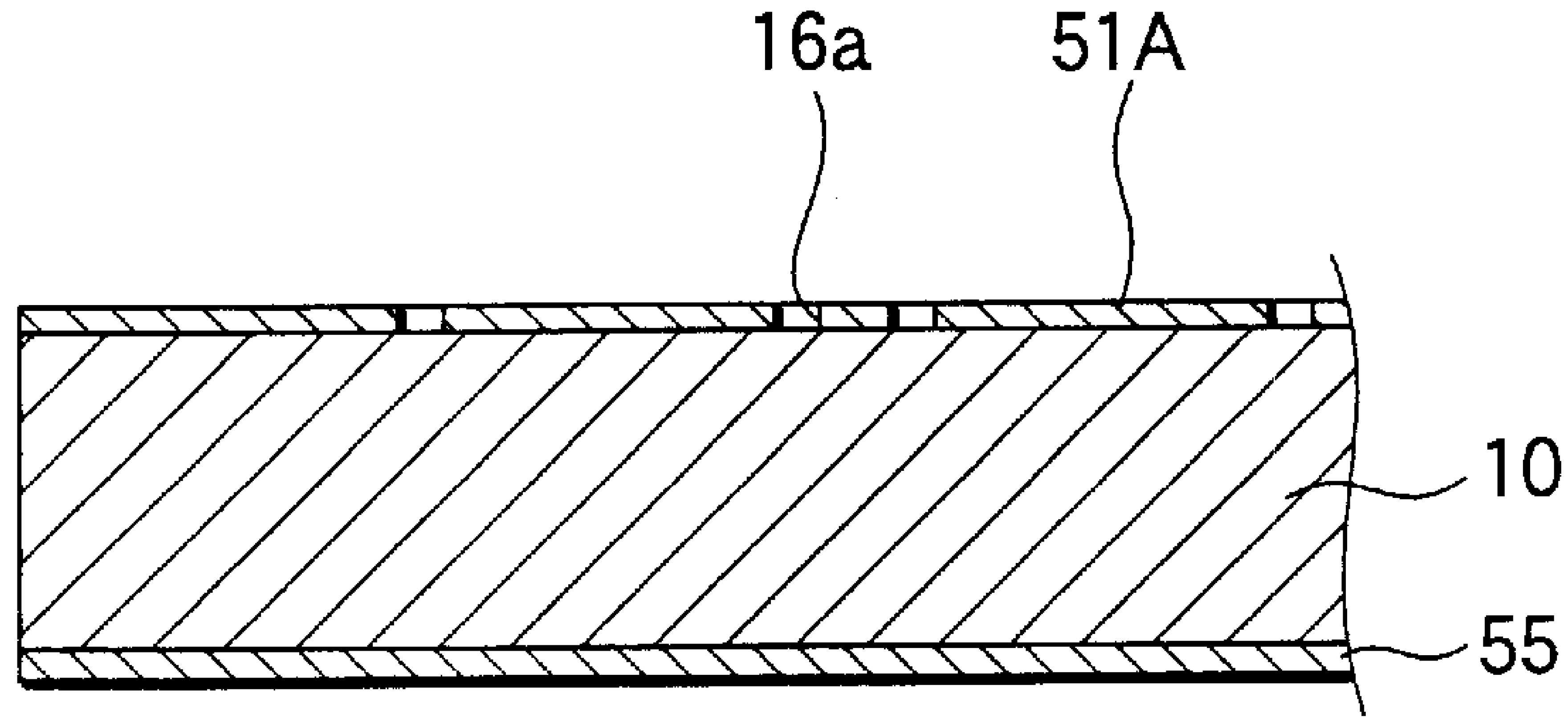


FIG.3B

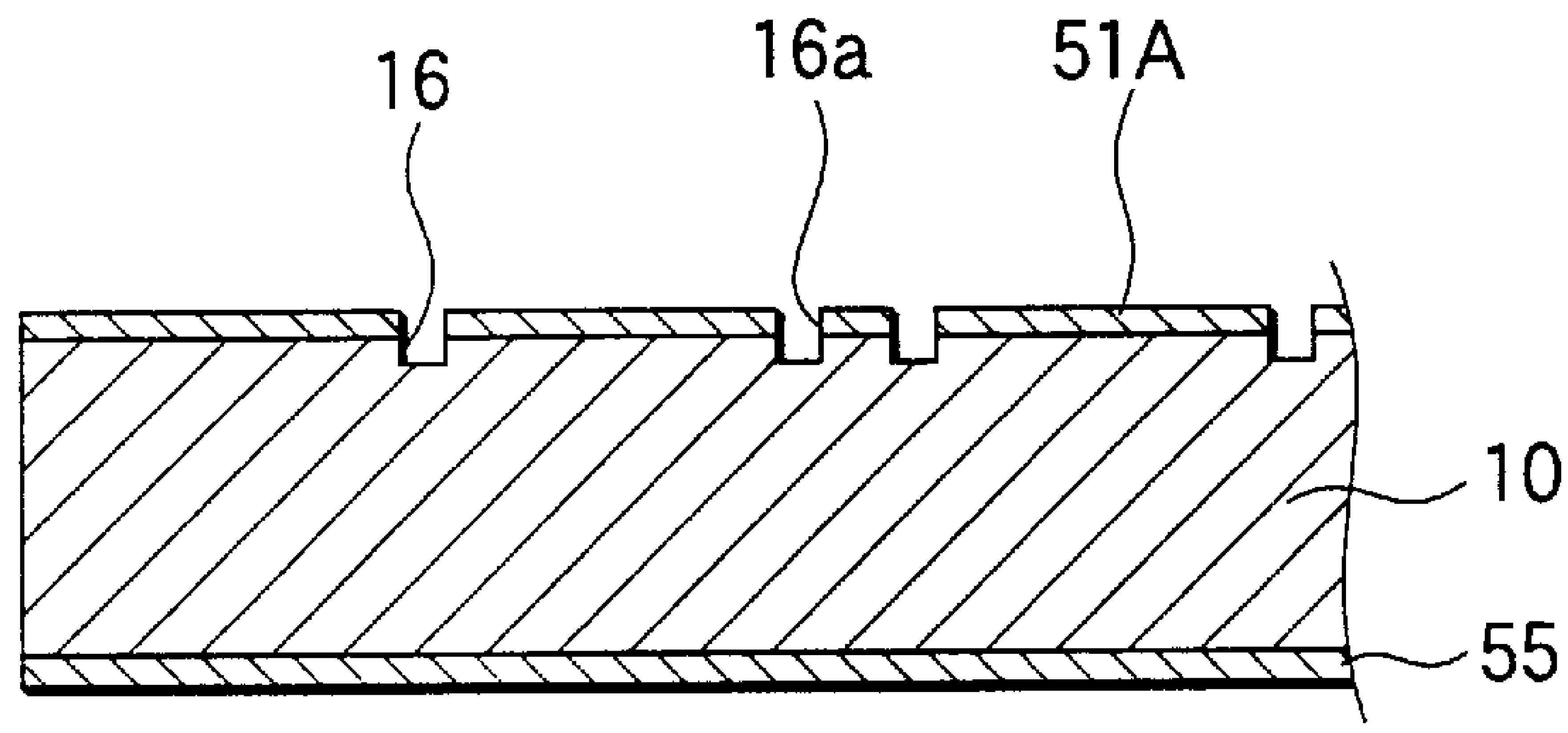


FIG.3C

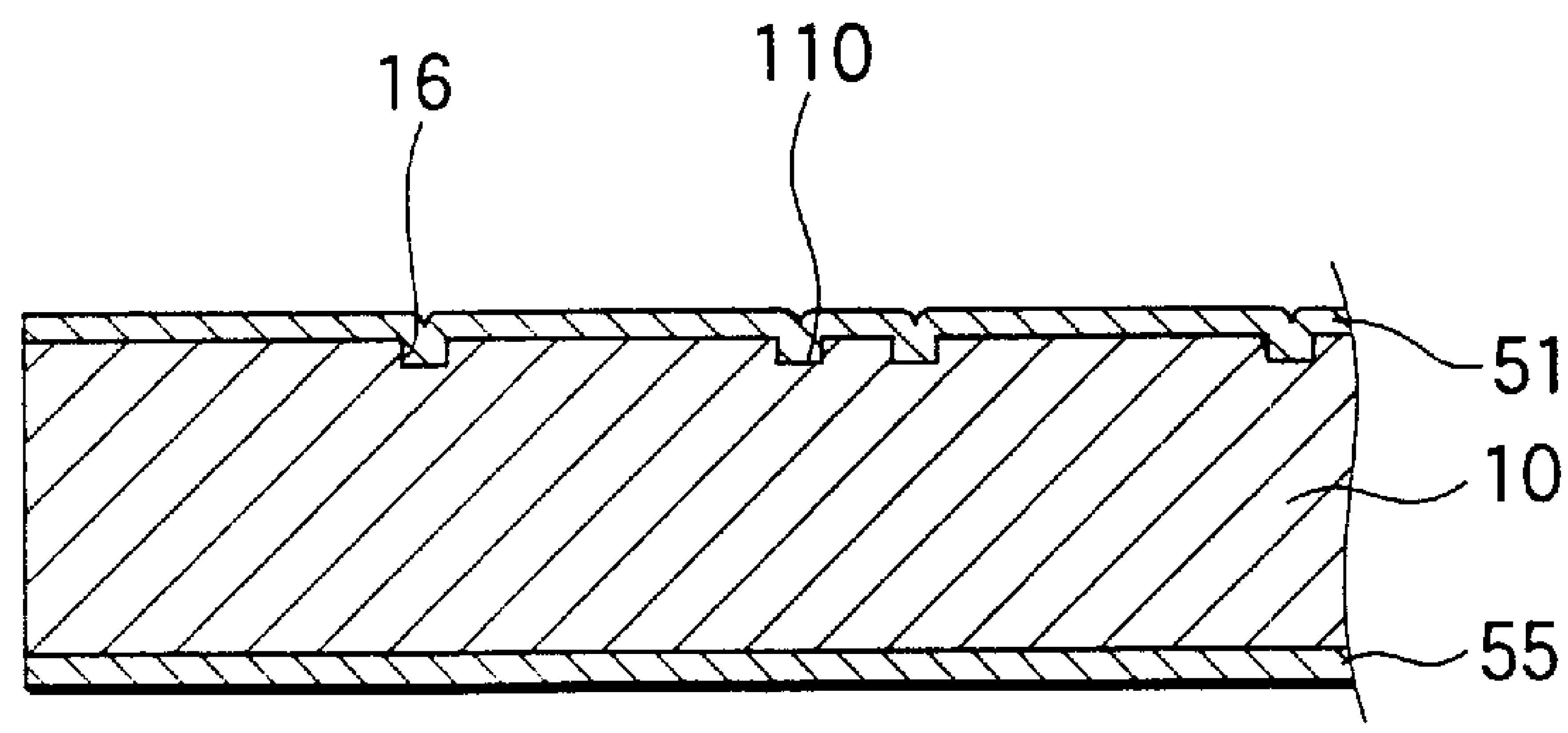


FIG.3D

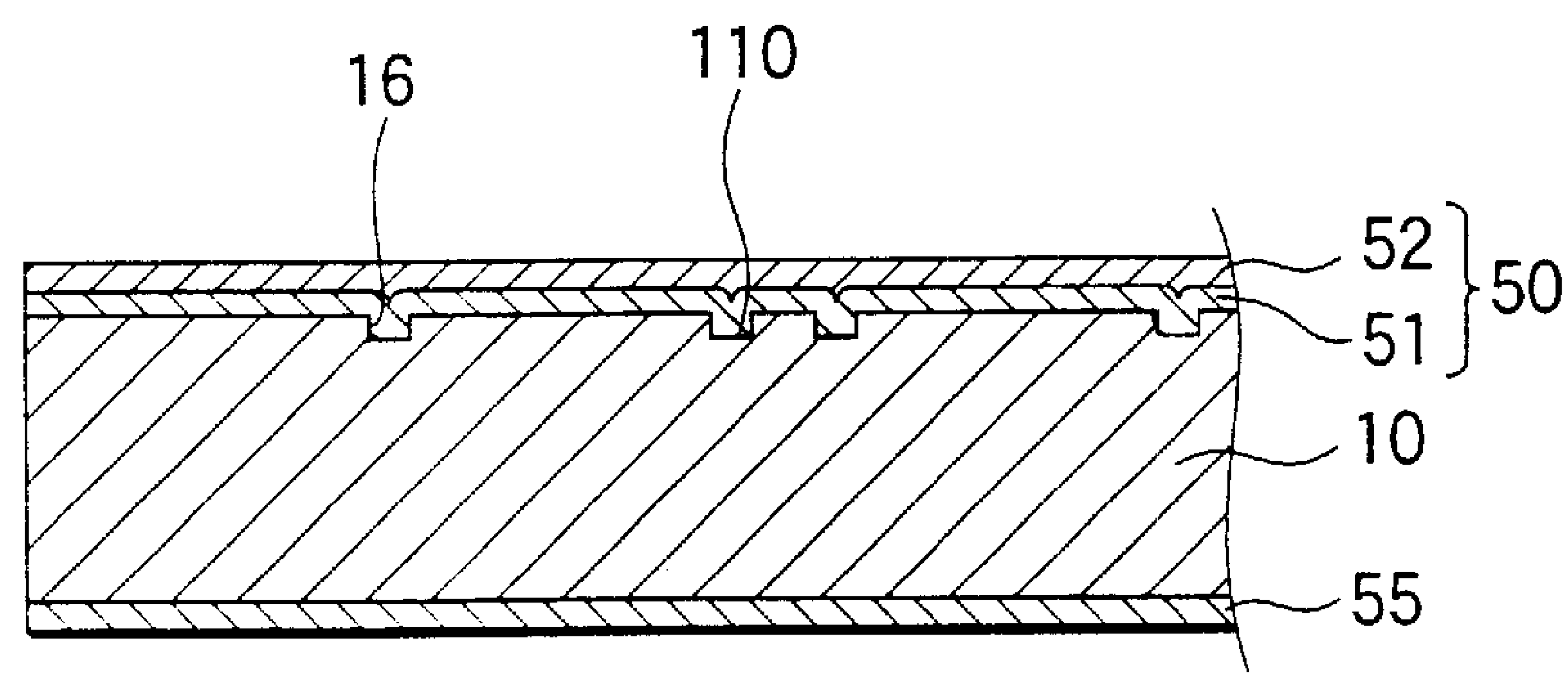


FIG.4A

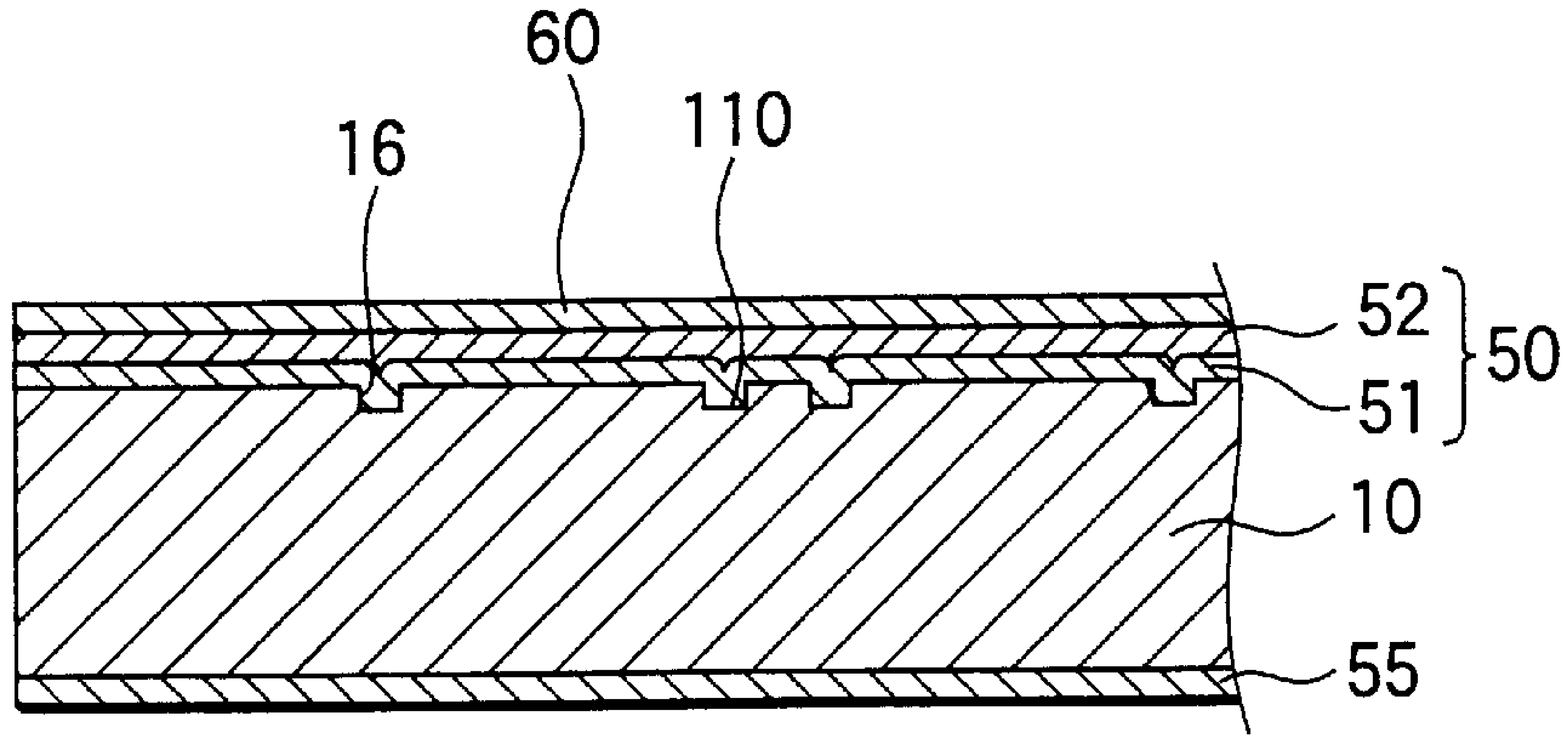


FIG.4B

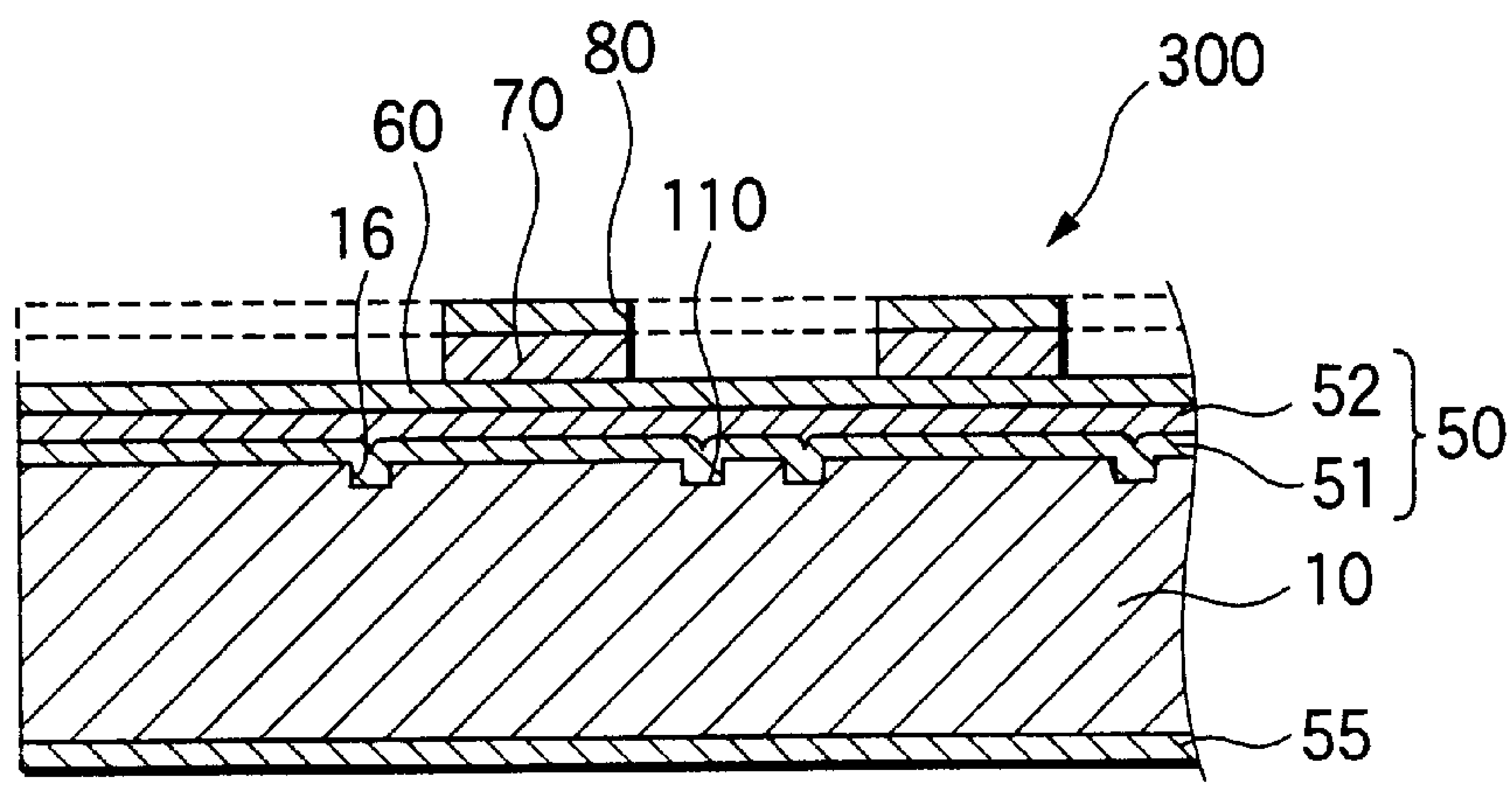


FIG.4C

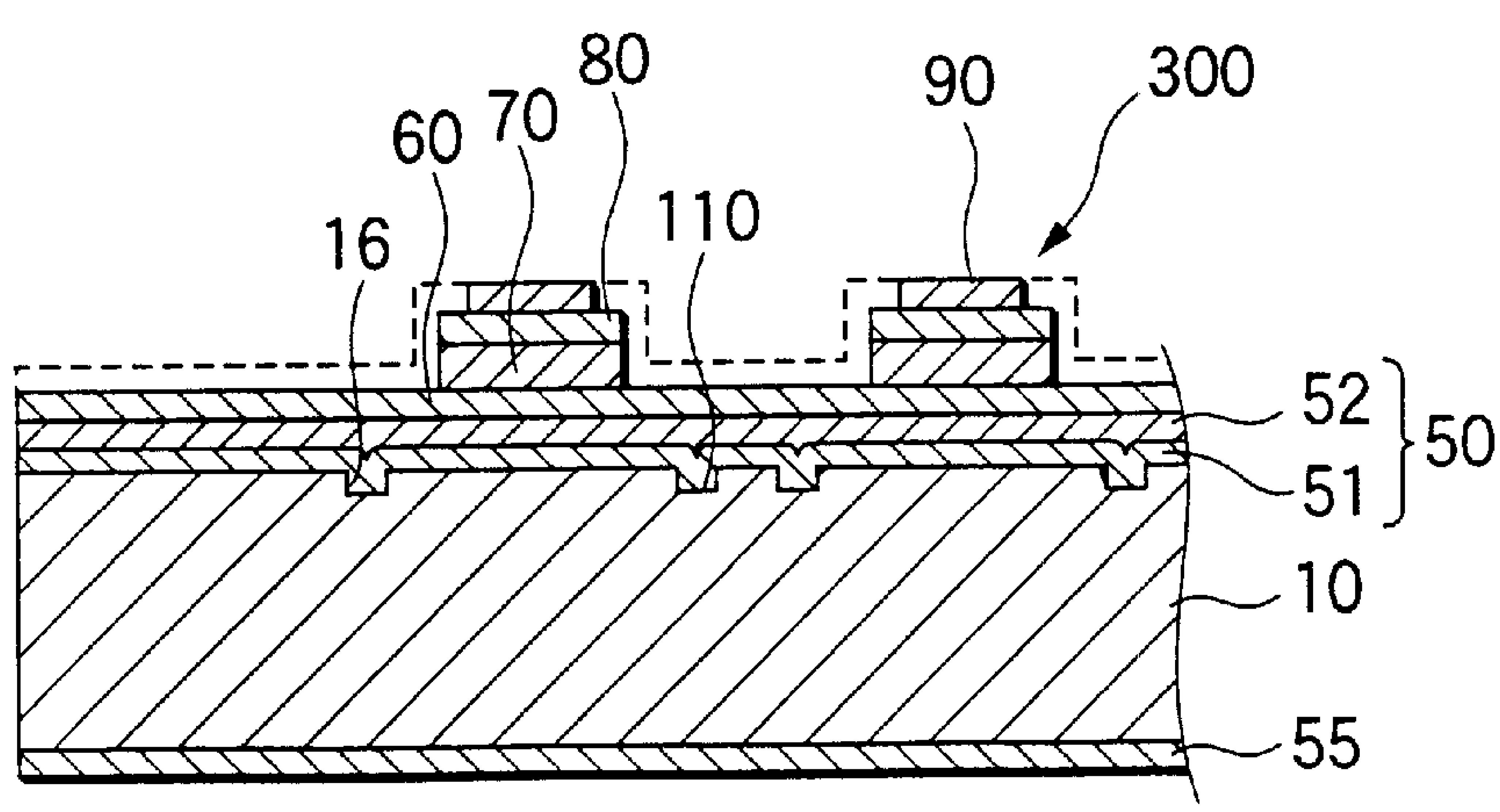


FIG.5A

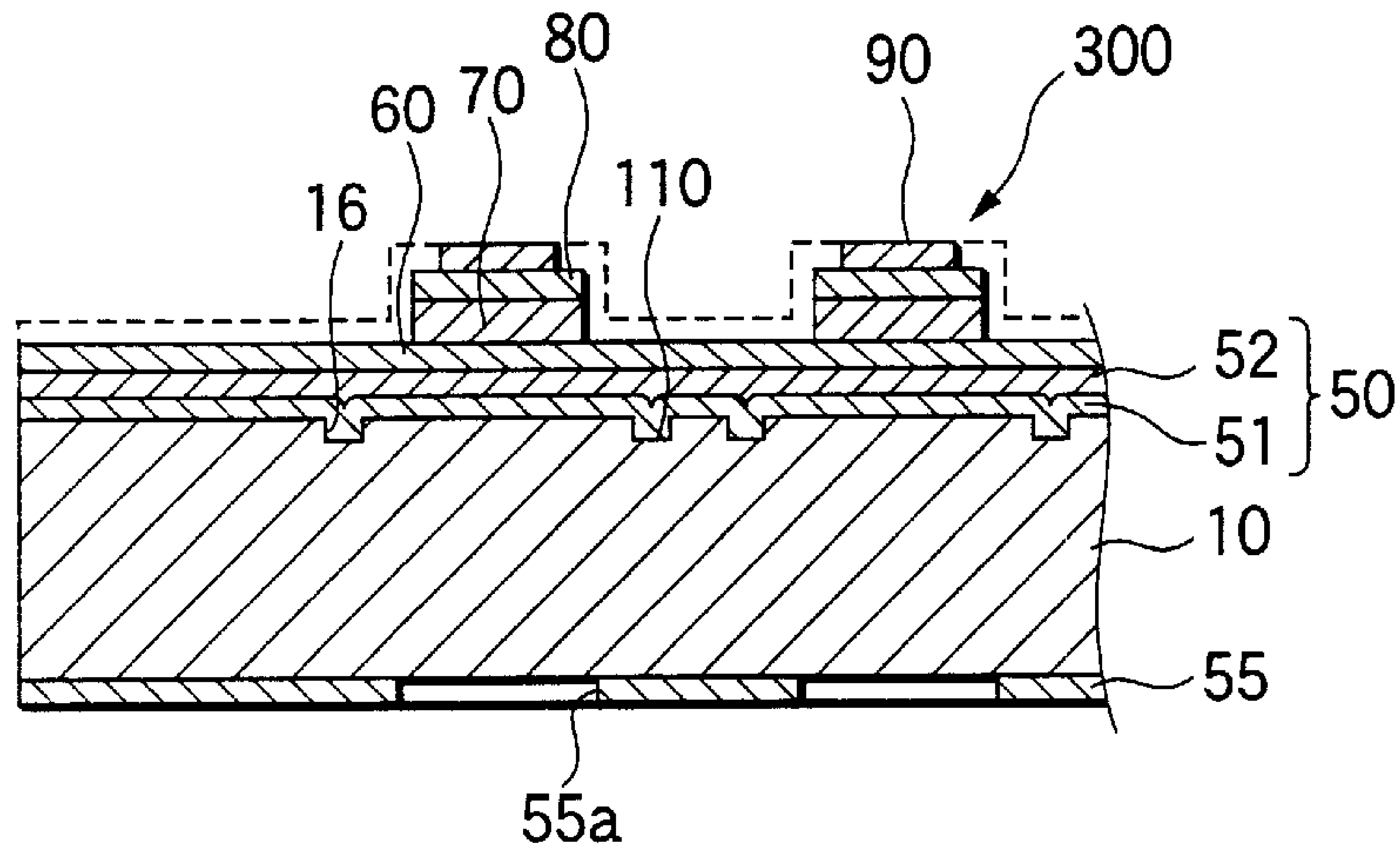


FIG.5B

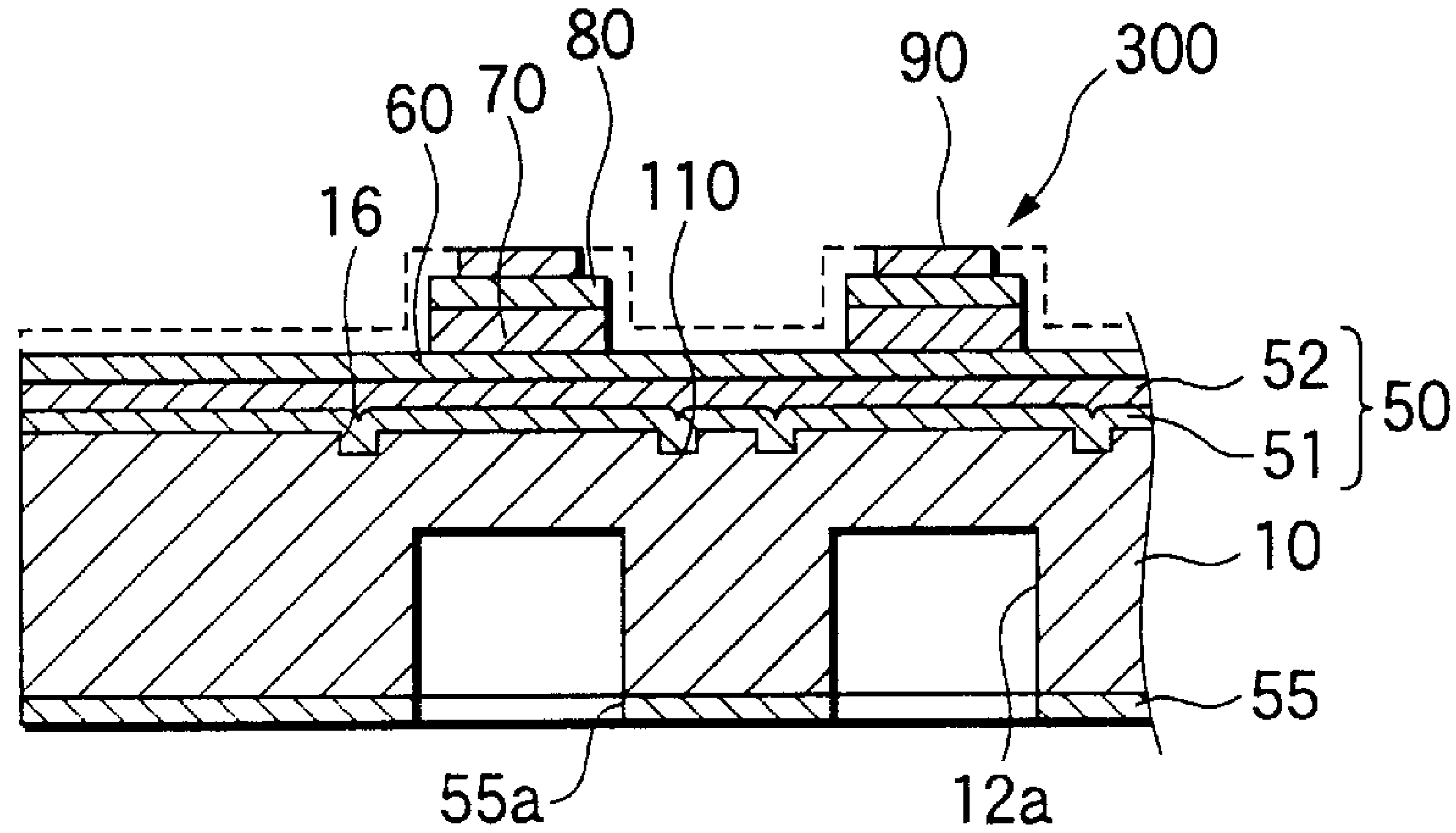


FIG.5C

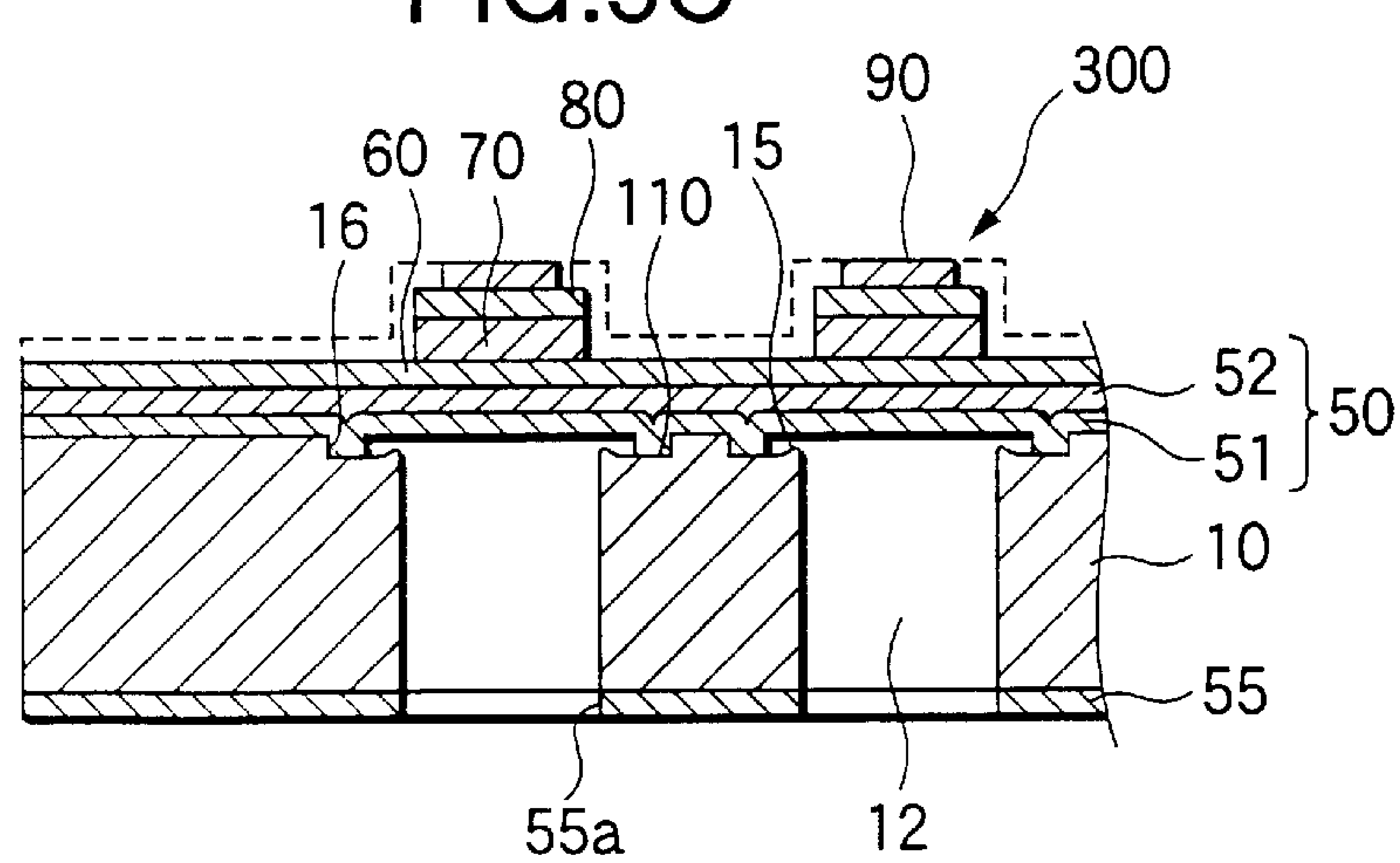
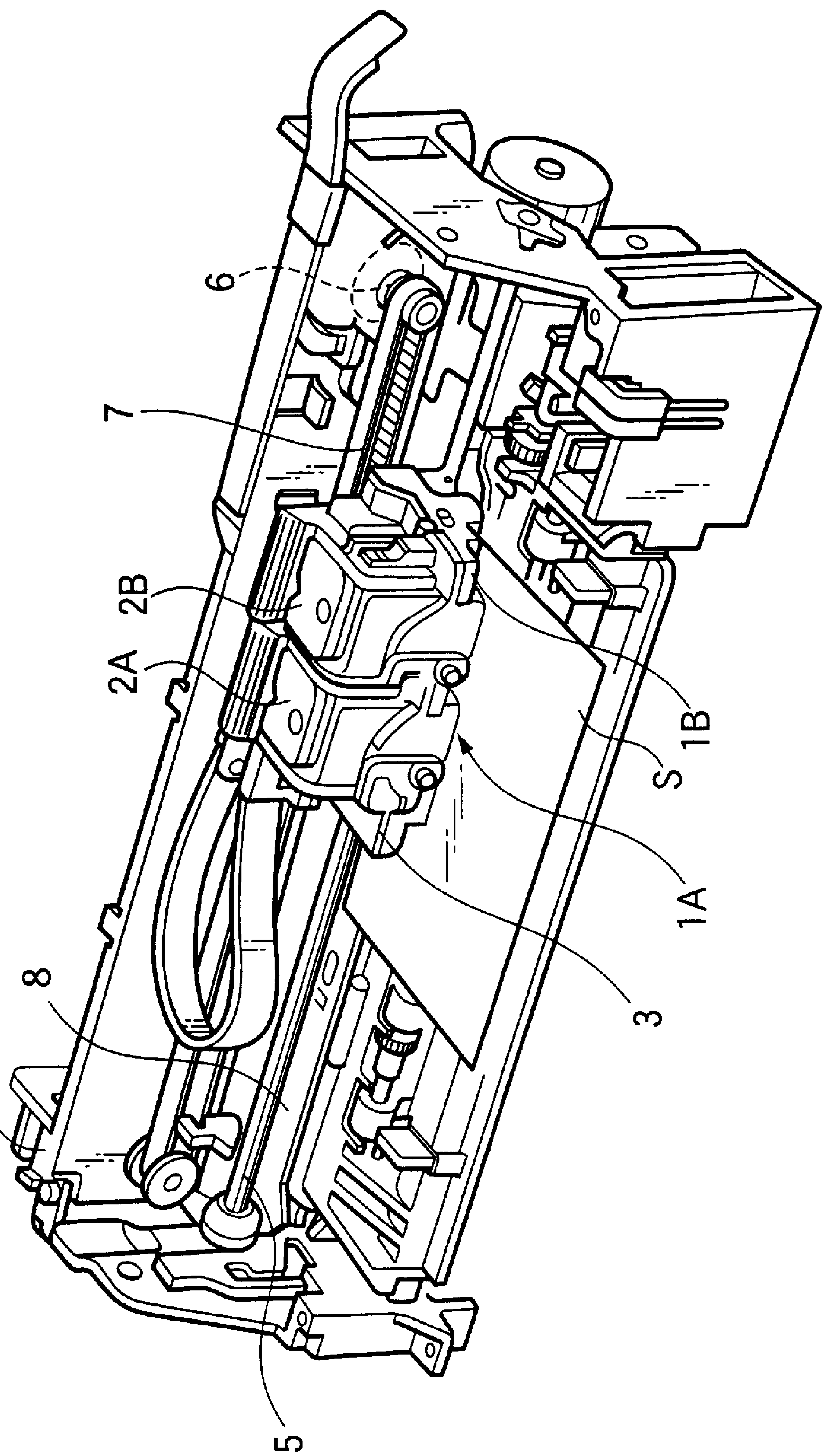


FIG.6



INK JET RECORDING HEAD AND METHOD OF MANUFACTURING THE SAME, AND INK JET RECORDING APPARATUS

BACKGROUND OF THE INVENTION

The present invention relates to an ink jet recording head in which a part of each pressure generating chamber communicating with nozzle orifices for ejecting ink droplets is formed with a vibration plate, a piezoelectric element is provided on the vibration plate interposed, and an ink droplet is ejected by a displacement of the piezoelectric element and a method of manufacturing the recording head, and an ink jet recording apparatus.

The ink jet recording head in which a part of each pressure generating chamber communicating with nozzle orifices for ejecting ink droplets is formed with a vibration plate, and the vibration plate by the piezoelectric element is deformed to pressurize ink in the pressure generating chamber to eject an ink droplet through the nozzle orifice, is known. This type of recording head is categorized into two types of recording heads; one uses the piezoelectric actuators of the longitudinal vibration mode in which the piezoelectric element axially expands and shrinks, and the other uses the piezoelectric actuators of the flexural vibration mode. Those types of recording heads have been put into practice.

The former recording head is advantageous in that the recording head suitable for the high density printing may be manufactured since the volume of the pressure generating chamber is varied by bringing the end face of the piezoelectric element into contact with the vibration plate. However, it has a difficult step of cutting the piezoelectric elements in a comb shape in alignment with the pitches of the nozzle orifice array, and needs another step of positioning and fixing the cut piezoelectric elements to the pressure generating chambers. In this respect, the manufacturing process is complex.

The latter recording head is advantageous in that the piezoelectric elements may be formed on the vibration plates in a relatively simple manner that a green sheet of piezoelectric material is bonded onto the vibration plates in conformity with a shape of the pressure generating chambers, and then baked. However, this recording head is disadvantageous in that since the flexural vibration is utilized, an area of some extent must be secured for each the piezoelectric element. Accordingly, it is difficult to array the piezoelectric elements at high density.

To solve the disadvantage of the latter recording head, there is proposed a technique in which a piezoelectric layer is uniformly formed over the entire surface of the vibration plate, and the piezoelectric layer is cut by a lithography process to form individual piezoelectric elements for each pressure generating chamber in accordance with arrangements of the pressure generating chambers (see JP-A-5-286131).

This technique enables to eliminate the work of bonding the piezoelectric elements to the vibration plates. Accordingly, the piezoelectric elements may be manufactured by a precise and simple process, using the lithography process. Additionally, the piezoelectric element is thinned and hence driven at high speed.

In such an ink jet recording head, the pressure generating chambers are formed penetrating the passage forming substrate in a manner that the passage forming substrate is selectively etched by anisotropic etching process from a surface of the passage forming substrate opposite to the piezoelectric-elements to the vibration plate.

When the anisotropic etching process is carried out in the form of a wet etching process using an alkaline aqueous solution, the alkaline aqueous solution or etching reaction products penetrate through the vibration plate to damage the piezoelectric elements, at the end of the etching process.

In the dry etching process, the etching is terminated indefinitely, therefore it is difficult to control the width of the vibration plate side of the pressure generating chamber. Accordingly, the pressure generating chambers cannot be formed with high accuracy by the dry etching process.

Further, in such an ink jet recording head, the pressure generating chambers are formed by the etching after the piezoelectric elements are formed. Accordingly, a position of the vibration plate side of the pressure generating chamber is instable by the dispersion in verticality of the pressure generating chambers. An accuracy of a relative position shift of the piezoelectric element to the pressure generating chambers is low, so that the ink ejecting characteristic and stability are low.

SUMMARY OF THE INVENTION

An object of the present invention is to provide an ink jet recording head having highly reliable piezoelectric elements and the improved ink ejecting characteristic and stability and a method of manufacturing the same, and an ink jet recording apparatus.

In one broad aspect of the invention, there is provided a first ink jet recording head having a passage forming substrate made of a silicon monocrystalline substrate including at least one pressure generating chamber communicating with a nozzle orifice; a vibration plate provided on a surface of the passage forming substrate; a piezoelectric element provided on the vibration plate having a lower electrode film, a piezoelectric layer and an upper electrode; a wide portion provided in the pressure generating chamber on a side of the vibration plate, extending in a longitudinal direction of the pressure generating chamber, a groove formed on a side of the wide portion, extending in a longitudinal direction of the wide portion; and an etching stop layer provided in the groove, defining a side wall of the wide portion as viewed in the width direction thereof to restrict the spread of the etching in the width direction.

In the first ink jet recording head, the width of the wide portion of the pressure generating chamber is restricted easily and reliably by the etching stop layer. As a result, the pressure generating chamber is manufactured highly accurately.

In a second ink jet recording head, the etching stop layer has each an insulating property.

In the second ink jet recording head, since the etching stop layer has an insulating property, no current leaks to the ink in the pressure generating chamber.

In a third ink jet recording head, the etching stop layer is made of the same material as that of a part of the vibration plate.

In the third ink jet recording head, the etching stop layer is made of the same material as that of a part of the vibration plate. Accordingly, the manufacturing process is simplified.

In a fourth ink jet recording head, the etching stop layer is made of silicon oxide.

In the fourth ink jet recording head, the etching stop layer is formed easily and reliably.

In a fifth ink jet recording head, the width of each groove is selected to be smaller in value than a value which is two times as large as the thickness of the etching stop layer.

In the fifth ink jet recording head, the etching stop layer is reliably formed within the groove.

In a sixth ink jet recording head, at least the vibration plate side of the pressure generating chambers are formed by anisotropic dry etching process.

In the sixth ink jet recording head, the piezoelectric element is reliably prevented from being damaged by an etching solution or etching reaction product, and the pressure generating chamber is manufactured highly accurately.

In another broad aspect, there is provided an ink jet recording apparatus being provided with the first to sixth ink jet recording head as described above.

The thus constructed ink jet recording apparatus is improved in the ink ejecting characteristics.

In yet another broad aspect, there is provided a method of manufacturing an ink jet recording head having a passage forming substrate consisting of a silicon monocrystalline substrate in which pressure generating chambers communicating with nozzle orifices are formed, and communicating with nozzle orifices are formed, and piezoelectric elements being formed on one of surfaces of the passage forming substrate with vibration plates interposed therebetween, each piezoelectric element including a lower electrode film, a piezoelectric layer and an upper electrode, which are formed with thin films formed by film forming and lithography processes. The method preferably comprises the steps of: forming grooves on both sides of each region at which the pressure generating chamber is to be formed in one of surfaces of the passage forming substrate, the grooves extending in the longitudinal direction; forming, in the grooves, etching stop layers which restrict the etching of the passage forming substrate; forming the piezoelectric elements by successively laminating the lower electrodes, the piezoelectric layers and the upper electrodes on one of the surfaces of the passage forming substrate with vibration plates being interposed therebetween, and by patterning the resultant structure; and forming the pressure generating chamber by etching out at least the vibration plate side of the passage forming substrate by the anisotropic dry etching process till the etching stop layers are exposed.

In the method of manufacturing the ink jet recording head, the spread of the etching in the width direction of the vibration plate side of the pressure generating chamber is easily controlled, so that the pressure generating chambers are manufactured highly accurately.

In another ink jet recording head manufacturing method, in the pressure generating chamber forming step, the passage forming substrate is subjected to anisotropic wet etching, and then anisotropic dry etching, thereby forming the pressure generating chambers.

In this method of manufacturing the ink jet recording head, the pressure generating chambers are formed by anisotropic wet etching and anisotropic dry etching. Accordingly, the time taken for etching may be reduced, and its manufacturing cost is reduced.

In yet another ink jet recording head manufacturing method, the etching stop layers have each an insulating property.

In the method of manufacturing the ink jet recording head, since the etching stop layers have each an insulating property, no current leaks to the ink in the pressure generating chambers.

In yet another ink jet recording head manufacturing method, the etching stop layers are made of the same material as that of a part of the vibration plate.

In the method of manufacturing the ink jet recording head, the etching stop layers are made of the same material as that of a part of the vibration plate. Accordingly, the manufacturing process is simplified.

In another ink jet recording head manufacturing method, the etching stop layers are made of silicon oxide.

In the method of manufacturing the ink jet recording head, the etching stop layers are formed easily and reliably.

In a further ink jet recording head manufacturing method, in the step of forming the grooves, the width of each groove is selected to be smaller in value than a value which is two times as large as the thickness of the etching stop layer.

In the method of manufacturing the ink jet recording head, the etching stop layers are reliably formed within the grooves.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. **1** is a perspective view showing an ink jet recording head according to an embodiment 1 of the present invention;

FIG. **2** is a cross sectional view showing the ink jet recording head according to the embodiment 1 of the invention; FIG. **2**A is a cross sectional view showing a pressure generating chamber, the illustration being viewed in the longitudinal direction, and FIG. **2**B is a cross sectional view showing taken on line A—A' in FIG. **2**A;

FIGS. **3**A–**3**D are cross sectional views showing a method of manufacturing the ink jet recording head according to the embodiment 1 of the invention, the illustration being as viewed in a direction in which pressure generating chambers are arranged side by side;

FIGS. **4**A–**4**C are cross sectional views FIG. **4** is a cross sectional view showing a method of manufacturing the ink jet recording head according to the embodiment 1 of the invention, the illustration being as viewed in a direction in which pressure generating chambers are arranged side by side;

FIGS. **5**A–**5**C are cross sectional views showing a method of manufacturing the ink jet recording head according to the embodiment 1 of the invention, the illustration being as viewed in a direction in which pressure generating chambers are arranged side by side; and

FIG. **6** is a perspective view showing the ink jet recording head according to the embodiment of the invention.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

The preferred embodiments of the present invention will be described with reference to the accompanying drawings.

Embodiment 1

FIG. **1** is an exploded view showing an ink jet recording head according to an embodiment 1 of the present invention. FIG. **2**A is a cross sectional view showing a pressure generating chamber, the illustration being viewed in a direction in which the pressure generating chambers are arranged side by side in the ink jet recording head. FIG. **2**B is a cross sectional view showing taken on line A—A' in FIG. **2**A.

As shown, a passage forming substrate **10** consists of a silicon monocrystalline substrate having a face **(110)** in the embodiment. One of the surfaces of the passage forming substrate **10** is an opened surface, and an elastic film **50** forming one of the surfaces of the pressure generating chamber **12** is formed on the other surface.

In the embodiment, the elastic film **50** is formed with a first elastic film **51** which is made of silicon dioxide (SiO_2) and formed on the passage forming substrate **10**, and a second elastic film **52** which is zirconium dioxide (ZrO_2) and formed on the first elastic film **51**. It is not essential that the elastic film **50** is made up of a plurality of layers.

Pressure generating chambers **12**, which are formed by an anisotropic etching process and partitioned by a plurality of partitioning walls **11**, are arranged side by side in the widthwise direction. A wide portion **15** is formed, by an anisotropic dry etching process, on the elastic film **50** side of each pressure generating chamber **12**. The wide portions, each extending in the widthwise direction of the pressure generating chamber **12**, and are arranged in the longitudinal direction of the pressure generating chamber **12**.

Grooves **16**, while extending in the longitudinal direction of the pressure generating chamber **12**, are each formed on both sides of each wide portion **15**. An etching stop layer **110** is put in the groove **16**. The side faces of each wide portion **15** are defined by the etching stop layers **110**.

The pressure generating chambers **12** having the wide portions **15** are formed in the following manner. Part of the pressure generating chambers are formed by applying anisotropic wet etching to the passage forming substrate **10** from one of the surfaces of the passage forming substrate to a region thereof near the elastic film **50**. Thereafter, anisotropic dry etching is applied thereto till the etching stop layers **110** are exposed.

The etching stop layers **110** are provided for restricting the spread of the etching in the width direction of the wide portions **15** of the pressure generating chambers **12** when the pressure generating chambers **12** are formed in the passage forming substrate **10** by anisotropic dry etching. The etching substantially stops when the etching of the passage forming substrate **10** progresses till the etching stop layer **110** is exposed. A material of the etching stop layer. **110** may be any material if it has an insulating property and is not etched by the anisotropic dry etching. For example, in the embodiment, a part of the first elastic film **51** is used as the etching stop layer **110** in a manner that the first elastic film **51** made of silicon dioxide, provided on the passage forming substrate **10**, is filled into the grooves **16**.

Thus, the etching stop layer **110** is provided on the passage forming substrate **10**, thereby restricting the width of each wide portions **15** of the pressure generating chambers **12**. With this feature, even if a position of the elastic film **50** side of the pressure generating chamber **12** is made instable by the dispersion in verticality of the pressure generating chambers **12**, a tolerance of a relative position shift of the piezoelectric element may be made large.

A protecting film **55** formed with a silicon dioxide layer is formed on the surface of the opened surface of the passage forming substrate **10**, by thermally oxidizing the surface of the passage forming substrate **10**. A nozzle plate **20** with nozzle orifices **21** formed therein is bonded onto the protecting film **55** with adhesive, a thermal deposition film or the like being interposed therebetween. The nozzle plate **20** has a thickness of 0.1 to 1 mm, and is made of glass, monocrystalline silicon, stainless steel (SUS) or the like, whose expansion coefficient is 2.5 to 4.5[$\times10^{-6}$/° C.] at 3000° C. The nozzle plate **20** entirely covers one of the surfaces of the passage forming substrate **10**, and also serves as a reinforcing plate for protecting the passage forming substrate **10** consisting of a silicon monocrystalline substrate against impact and external force applied thereto.

Additionally, the pressure generating chambers **12** is connected to a common ink chamber **31** via ink supply ports **22**, which are formed at positions corresponding to the first ends of the pressure generating chambers **12** of the nozzle plate **20**. Ink is supplied from the common ink chamber **31** to the pressure generating chambers **12**, through the ink supply ports **22**.

An ink introducing port **23** through which ink is supplied from exterior to the common ink chamber **31** is formed in a part protruded from an end of the passage forming substrate **10** of the nozzle plate **20**.

An ink-chamber forming plate **30** and an ink chamber side plate **40**, which cooperatively form the common ink chamber **31**, are joined to a part of the nozzle plate **20** which contains the ink supply ports **22** and the ink introducing port **23**.

The ink-chamber forming plate **30** forms the periphery wall of the common ink chamber **31**, and is formed by punching a stainless plate having a thickness, which is appropriately determined depending on the number of nozzle orifices and the ink ejection frequency. In the embodiment, a thickness of the ink-chamber forming plate **30** is 0.2 mm.

The ink chamber side plate **40** is formed with a stainless plate, and one of its surfaces forms one sidewall of the common ink chamber **31**. The ink chamber side plate **40** is half-etched to form a recess **40***a* in a part of the other surface, whereby a thin wall **41** is formed. The thin wall **41** is provided for absorbing a pressure, which is generated at the time of ejecting the ink droplet and acts toward the side opposite to the nozzle orifices **21**. And it prevents an unnecessary positive or negative pressure from acting on the other pressure generating chamber **12** by way of the common ink chamber **31**.

The size of the pressure generating chamber **12** for applying the pressure to the ink for ejection and the size of the nozzle orifices **21** for ejecting ink droplets are optimized in accordance with the amount of ink droplet ejected, ejecting speed, and ejection frequency. In the recording of 360 ink droplets per inch, it is necessary to accurately form the nozzle orifices **21** each having a diameter of several tens μm.

A lower electrode film **60** of about 0.2 μm thick, a piezoelectric layer **70** of about 1 μm thick, and an upper electrode **80** of about 0.1 μm are laminated on the elastic film **50** of the passage forming substrate **10** by a process to be described later, whereby a piezoelectric element **300** is formed. Here, the piezoelectric element **300** indicates a portion including the lower electrode film **60**, piezoelectric layer **70** and upper electrode **80**. Generally, the piezoelectric element **300** is formed such that either of the electrodes is used as a common electrode, and the other electrode and the piezoelectric layer **70** are patterned every pressure generating chamber **12**. In the specification, a portion which includes the electrode and piezoelectric layer **70** as patterned, and will be piezoelectrically distorted when voltage is applied to between both the electrodes, will be referred to as a piezoelectric-material active part. In the present embodiment, the lower electrode film **60** is used as a common electrode of the piezoelectric element **300**, the upper electrodes **80** are individual electrodes of the piezoelectric element **300**. However, the former may be used as the individual electrodes and the latter may be used as the common electrode at the convenience of designing the drive circuit and wiring require. If so done, no problem arises. In either case, the piezoelectric-material active part is formed every pressure generating chamber. In the specification, a combination of the piezoelectric element **300** and the vibration plate in which a displacement is caused wen the piezoelectric element **300** is driven, will referred to as a piezoelectric actuator. In the embodiment mentioned above, the elastic film **50** and the lower electrode film **60** serve as the vibration plate, and the lower electrode film may additionally have a function of the elastic film.

The upper electrodes **80** as the individual electrodes of the piezoelectric element **300** are connected to an external wiring through lead electrodes **90**, which extend on the elastic film **50** from one end of the piezoelectric element **300** as viewed in the longitudinal direction.

The thus constructed ink jet recording head of the embodiment operates in the following way. Ink is introduced into the head through the ink introducing port **23** connecting to an external ink supplying device (not shown). After the ink flow structure ranging from the common ink chamber **31** to the nozzle orifices **21** is filled with the ink. Voltage is applied to between the lower electrode film **60** and the upper electrode **80** of each pressure generating chamber **12** in accordance with a recording signal derived from an external drive circuit (not shown). The elastic film **50**, lower electrode film **60** and piezoelectric layer **70** are flexurally deformed. As a result, a pressure within each pressure generating chamber **12** increases, then an ink droplet is ejected from the nozzle orifice **21** associated therewith.

A method of manufacturing an ink jet recording head thus constructed will be described in detail. FIGS. **3** to **5** show, in cross sectional views in a direction in which pressure generating chambers are arranged side by side, the method of manufacturing the ink jet recording head.

As shown in FIG. **3**A, a wafer of a silicon monocrystalline substrate, which will be a passage forming substrate **10**, is thermally oxidized in a diffusion being set at about 1100° C. A mask **51**A made of silicon oxide is formed on one of the surfaces of the passage forming substrate **10**, and is patterned to form openings **16***a* therein. At the same time, a protecting film **55** made of silicon dioxide is formed on the other surface of the passage forming substrate.

Subsequently, as shown in FIG. **3**B, grooves **16** are formed in the passage forming substrate **10** by anisotropic etching, by using the mask **51**A having he openings **16***a* formed therein as a mask pattern.

In this case, the anisotropic etching maybe anisotropic wet etching or anisotropic dry etching, and the etching is not limited to the anisotropic etching.

As shown in FIG. **3**C, the passage forming substrate **10** is thermally oxidized again, and another first elastic film **51** made of silicon oxide is formed on the one surface of the passage forming substrate **10**. At this time, the first elastic film **51** is formed entirely covering the inner surfaces of the grooves **16**, so that etching stop layers **110** made of silicon oxide are formed in the grooves **16**.

The first elastic film **51** is formed on the surface of the passage forming substrate **10**, while being substantially uniform in thickness. To fill the first elastic film **51** in the grooves **16**, it is preferable that the width of each groove **16** is selected to be smaller in value than a value which is two times as large as the thickness of the first elastic film **51**. By so selected, the first elastic film **51** reliably fills the grooves **16**.

In the embodiment, the first elastic film **51** and the protecting film **55** are formed by thermally oxidizing the passage forming substrate. Instead, it may be formed at a relatively low temperature, 350° C.–500° C., by a TEOS-CVD method. In the embodiment, the etching stop layers **110** are formed in the grooves **16** in a manner that the first elastic film **51** is formed covering the inner surfaces of the grooves **16**. In an alternative, the etching stop layers are formed in the grooves **16** by a material other than the first elastic film **51**, and then the first elastic film **51** is formed on the surface of the passage forming substrate **10** and the etching stop layers. The etching stop layers whose material is the same as that of the first elastic film **51** may be formed in a process step, which is different from the step of forming the first elastic film **51**, as a matter of course.

Next, as shown in FIG. **3**D, a second elastic film **52** is formed over the first elastic film **51**. In the present embodiment, a zirconium layer is formed on the first elastic film **51**, and is thermally oxidized in a diffusion being set at 500–1200° C., thereby forming a second elastic film **52** of zirconium dioxide. And the first elastic film **51** and the second elastic film **52** cooperate to form an elastic film **50**.

In the embodiment, the first elastic film **51** fills the grooves **16** such that it reaches the surface of the passage forming substrate **10** by using part of the first elastic film **51** for the etching stop layers **110**. Accordingly, the surface of the second elastic film **52** is substantially flat.

Subsequently, as shown in FIG. **4**A, a lower electrode film **60** is entirely formed on the elastic film **50** side of the passage forming substrate **10** by sputtering and is patterned into a predetermined shape. Platinum, iridium or the like is preferable as a material of the lower electrode film **60**. The reason for this is that a piezoelectric layer **70**, which will be described later and formed by a sputtering method or sol-gel method must be baked and crystallized at about 600 to 1000° C. in an air or oxygen atmosphere after the film formation. A material of the lower electrode film **60** must maintain its conductivity at such a high temperature and oxidizing atmosphere. In particular, in a case where lead zirconium titanate (PZT) is used for the piezoelectric layer **70**, it is preferable that the conductivity of the lower electrode film material is less varied by diffusion of the lead oxide. For those reasons, platinum or iridium is preferable for the lower electrode film material.

Subsequently, as shown in FIG. **4**B, a piezoelectric layer **70**. and an upper electrode film **80** are formed, and a piezoelectric element **300** is patterned by etching only of the piezoelectric layer **70** and the upper electrode film **80**.

In the embodiment, the piezoelectric layer **70** is formed by called sol-gel process, viz., in a manner that a sol which is formed by dissolving and dispersing metal organic into a catalyst is coated and dried into a gel, and the gel is baked at high temperature, whereby a piezoelectric layer **70** made of metal oxide is formed. PZT-based materials are preferable for the material of the piezoelectric layer **70** which it is used for an ink jet recording head. A film formation method is not limited for forming the piezoelectric layer **70**. Spin coating process such as sputtering method or metal organic deposition process (MOD) may be employed.

The following method may be employed. In the method, a percursor film of lead zirconium titanate is formed by a sol-gel process, sputtering or MOD process, and then is crystallized at low temperature by high pressure process in an alkaline solution.

High electrical conductivity materials such as aluminum, gold, nickel, platinum, or other metals and a conductive oxide may be used as a material of the upper electrode film **80**. In the embodiment, platinum is used for film formation by sputtering.

Next, lead electrodes **90** are formed entirely on the passage forming substrate **10** and patterned every piezoelectric element **300**, as shown in FIG. **4**C.

The film formation process is as mentioned above. Following the film formation, pressure generating chambers **12** are formed by anisotropic etching process.

As shown in FIG. **5**A, openings **55***a* are formed in a region of a protecting film **55** which is formed on the side of the passage forming substrate **10** opposite to the side thereof by patterning the region of the protecting film in which pressure generating chambers **12** are to be formed.

Subsequently, as shown in FIG. **5**B, recesses **12***a* which will be parts of the pressure generating chambers **12** are formed by anisotropic wet etching process by use of the protecting film **55** having openings **55***a* as a mask pattern.

Where the anisotropic wet etching is used, recesses **12***a* may be formed to have a predetermined depth without forming through holes in the passage forming substrate **10** by etching, if the half etching is used. Accordingly, there is no case that an alkaline aqueous solution used in the anisotropic wet etching or etching reaction products penetrate through the elastic film **50** to damage the piezoelectric elements **30**.

Then, as shown in FIG. **5**C, the recesses **12***a* as formed by anisotropic wet etching are continuously subjected to anisotropic dry etching process, to thereby form pressure generating chambers **12**.

In the anisotropic dry etching process, the etching is continued till the etching reaches the first elastic film **51**. In the anisotropic dry etching process, the etching indefinitely ends, so that the pressure generating chambers **12** spread in width along the first elastic film **51** to form wide portions **15**. At the time, the etching substantially stops in the width direction at a time point where the etching stop layers **110** formed in the grooves **16** are exposed. As a result, the wide portions **15** are formed on the elastic film **50** side of each pressure generating chamber **12** in a state that it extends in the widthwise direction of the pressure generating chamber **12** and has predetermined width.

It is satisfactory that the depth of each groove **16** is selected to be such a depth value, i.e., about 0.5 μm larger, as to prevent that when the pressure generating chambers are formed by the anisotropic dry etching process, the wide portions **15** formed on the elastic film **50** side exceed each beyond the etching stop layer **110** formed in the groove **16** and spread.

With this feature, even if a position of the vibration plate side of the pressure generating chamber **12** is made instable by the dispersion in verticality of the pressure generating chambers, a tolerance of a relative position shift between the piezoelectric element **300** and the pressure generating chambers **12** may be made large by providing the etching stop layers **110** to restrict the width of the wide portions **15** of the pressure generating chambers **12**.

Thus, in the embodiment, the first elastic film **51** fills the grooves **16** such that it reaches the surface of the passage forming substrate **10** by using the etching stop layer **110** made of the same material as of the first elastic film **51**, i.e., a part of the first elastic film **51**, and the surface of the second elastic film **52** is substantially flat. With this feature, there is eliminated the stress concentration by deformation of the piezoelectric element **300**, and hence the elastic film **50** is prevented from being broken.

The elastic film **50** side of the pressure generating chamber **12** is formed by the anisotropic dry etching process, and the opening side of the pressure generating chambers is formed by the anisotropic wet etching process. Accordingly, the piezoelectric element **300** is reliably prevented from being damaged. It is satisfactory that at least the elastic film **50** side of the pressure generating chambers **12** are formed by the anisotropic dry etching process. Accordingly, the pressure generating chambers **12** may be formed by the anisotropic dry etching process.

In this way, a number of chips are simultaneously formed on a single wafer by the sequential film forming steps and the anisotropic etching processes, and after the process ends, the wafer is divided into passage forming substrates **10** each of one chip size as shown in FIG. **1**. Then, a nozzle plate **20**, an ink-chamber forming plate **30** and an ink chamber side plate **40** are successively bonded to each of those passage forming substrates **10**, whereby a unit body or an ink jet recording head is formed.

Another Embodiment

While the ink jet recording head and the method of manufacturing the same, which are believed to be the preferred embodiments of the invention, have been described, it should be understood that the invention is not limited to such.

The ink jet recording head of the embodiment 1 forms a part of a recording head unit provided with ink passages communicating with the ink cartridges or the like, and is mounted on an ink jet recording apparatus. FIG. **6** shows an example of the ink jet recording head.

As shown in FIG. **6**, ink cartridges **2**A and **2**B, which form an ink supplying device, are detachably mounted on recording head units **1**A and **1**B provided with recording heads, respectively. A carriage **3** on which the recording head units **1**A and **1**B are mounted is axially movable along a carriage shaft **5** mounted on an apparatus body **4**. The recording head units **1**A and **1**B eject a black ink composition and color ink compositions, respectively.

A driving force by a drive motor **6** is transmitted to the carriage **3** by a way of a plurality of gears (not shown) and a timing belt **7**, so that the carriage **3** having the recording head units **1**A and **1**B mounted thereon is moved along the carriage shaft **5**. The head body **4** includes a platen **8** extending along the carriage **3**. The platen **8** is driven to rotate by a driving force of a paper feed motor (not shown). In this case, a recording sheet S as a recording medium of paper, which is fed by the feeding roller or the like, is wound on the platen **8**, and transported.

As seen from the foregoing description, wide portions are provided on the vibration plate side of the pressure generating chambers, and the etching stop layers for restricting the spread of the etching in the width direction of the wide portions, are formed in the passage forming substrate. With such a technical feature, the width of the wide portions of the vibration plate side of the pressure generating chambers are restricted by the etching stop layers. As a result, the pressure generating chambers are manufactured highly accurately, and the ink ejecting characteristic and stability are improved. In such a method of manufacturing pressure generating chambers, at least the vibration plate side of the pressure generating chambers are formed by the anisotropic dry etching process. Accordingly, the piezoelectric elements are not damaged, and hence piezoelectric elements improved in reliability may be manufactured.

What is claimed is:

1. An ink jet recording head comprising:

a passage forming substrate made of a silicon monocrystalline substrate including a pressure generating chamber communicating with a nozzle orifice;

a vibration plate provided on a surface of the passage forming substrate;

a piezoelectric element provided on the vibration plate having a lower electrode film, a piezoelectric layer and an upper electrode;

a wide portion provided in the pressure generating chamber on a side of the vibration plate, extending in a longitudinal direction of the pressure generating chamber,

a groove formed on a side of the wide portion, extending in a longitudinal direction of the wide portion; and an etching stop layer provided in the groove, defining a side wall of the wide portion as viewed in the width direction thereof to restrict the spread of the etching in the width direction.

2. The ink jet recording head according to claim **1**, wherein the etching stop layer has an insulating property.

3. The ink jet recording head according to claim **1**, wherein the etching stop layer is made of the same material as a part of the vibration plate.

4. The ink jet recording head according to claim **1**, wherein the etching stop layer is made of silicon oxide.

5. The ink jet recording head according to claim **1**, wherein a width of the groove is selected to be a smaller value than a value two times as large as the thickness of the etching stop layer.

6. The ink jet recording head according to **1**, wherein a part of the pressure generating chamber at the side of the vibration plate is formed by anisotropic dry etching process.

7. An ink jet recording apparatus being provided with the ink jet recording head according to any of claims **1** to **6**.

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